



# **Wi-Fi Module (XY3721-B3) Specification**

## **User Guide**

Version updated 2022-11-09

# 1 Product Overview

XZ421-F1 is a low power on board Wi-Fi module developed by Shenzhen Rinocloud Technology Co., Ltd. It is equipped with a BLE328M Bluetooth 5.2 and Wi-Fi 802.11n chip that can operate either as a standalone or as a slave to other MCUs. It can be loaded via a bootloading circuitry from a microcontroller when carrying external applications and acting as a core application processor. In the case of failure, it includes a low power ARM-Cortex-M0, 112K RAM, up to 120MHz main frequency, built-in 256KB SRAM, 2KByte flash and peripheral resources.

XZ421-F1 Wi-Fi module supports IEEE 802.11 b/g/n protocol scheme, BLE5.2, lightweight TCP/IP protocol stack, and S-A, M, AP+S-A modes. Users can use it as a module to access networking functions to existing devices or build an edge network terminals.

## 1.1 Features

- Built-in lightweight TCP/IP protocol stack
- Support 802.11 b/g/n / BLE5.2 scheme protocol
- Built-in IR serial, UART, I2C, SPI and integrated on-board antenna for compact with external antenna
- MCU up to 120MHz clock frequency + 256KBSRAM
- Built-in 2Vbatt - 1.8v

- 🚩 Support one-click firmware OTA upgrade, can start upgrading via mobile APP, telnet and
- 🚩 Support STAN/A-P-EIS working mode
- 🚩 Support WPA2/TKIP/PSK/WPA2 security protocol
- 🚩 Support 802.11a and 802.11b/g/n PS protocols
- 🚩 Support the Smart intelligent networking function
- 🚩 Support 2.4G and 802.11n40
- 🚩 Support On-chip hardware PS/PS
- 🚩 Voltage range 2.4V-2.5VDC, recommended to use 2.5V 500mA single power supply
- 🚩 3.5mm antenna compatible with external antenna

## 1.2 Main application fields

- Smart Lighting   Smart Home   Smart Sensing   Smart Office
- Smart Gateway   Smart Industry   Smart Home Appliances   Smart Security

## 2 Module Interface

### 2.1 Size Package

XY3721-B3W - module has 2 rows of pins, total 22 pins, pin pitch: 2mm, XY3721-B3W - module size:  $18 \pm 0.35\text{mm}$  (top)  $\times$   $24 \pm 0.35\text{mm}$  (bottom)  $\times$   $3.0 \pm 0.25\text{mm}$  (thickness), PCB thickness:  $0.8 \pm 0.1\text{mm}$ , package as shown in figure 2.1:



Top View



Bottom View

## 2.2 Pin Definition

The pin definition is defined in table 2.1.

Pin No.	Symbols	I/O Types	Function
	VST		analog signal input (5V), power management and VBAT pin
1	AD0	I/O	8260 I/O with enable pin, enables normal I/O operation to 425 of 0
2	TK		analog multiplexer, internal 1.2V, operates as a multiplexer with a module output
4	P00	I/O	external command, corresponding to 425 of 0
5	P01	I/O	external command, 100ns 425 of 0, subject to capacity 100ns 425 of 0
6	P02	I/O	external command, 100ns 425 of 0, subject to capacity 100ns 425 of 0
7	P03	I/O	external command, 100ns 425 of 0, subject to capacity 100ns 425 of 0
8	VCC1	I	analog to digital converter, internal supply
9	VCC2	I	analog to digital converter, internal supply
10	P04	I/O	external command, 100ns 425 of 0, subject to capacity 100ns 425 of 0
11	TXD0	I/O	external command, 100ns 425 of 0, subject to capacity 100ns 425 of 0
12	CS0	I/O	external command, 100ns 425 of 0, subject to capacity 100ns 425 of 0
13	P05	I/O	external command, 100ns 425 of 0, subject to capacity 100ns 425 of 0
14	P06	I/O	external command, 100ns 425 of 0, subject to capacity 100ns 425 of 0
15	VCC3	I	analog to digital converter, internal supply, 100ns 425 of 0
16	TXD1	I/O	external command, 100ns 425 of 0, subject to capacity 100ns 425 of 0
17	P07	I/O	external command, 100ns 425 of 0, subject to capacity 100ns 425 of 0
18	VCC4	I	analog to digital converter, internal supply, 100ns 425 of 0
19	P08	I/O	external command, 100ns 425 of 0, subject to capacity 100ns 425 of 0
20	P09	I/O	external command, 100ns 425 of 0, subject to capacity 100ns 425 of 0
21	P	I/O	external command, 100ns 425 of 0, subject to capacity 100ns 425 of 0
22	P10	I/O	external command, 100ns 425 of 0, subject to capacity 100ns 425 of 0

Note: VCC indicates power supply pin, I/O indicates input and output pin, AD0 indicates analog pin.

## 3 Electrical parameters

Parameter	Nominal value
Operating Temperature	-40°C ~ 85°C (max)
Working voltage	WTF2000: 1.8V ~ 3.3V
Storage voltage	Operating PCB and module IPX and the others
Storage temperature	-55°C ~ +125°C
Storage voltage	0V ~ 3.3V
Storage voltage change (time mode)	±0.2% / 15°C / 40s
Storage voltage change (pulse mode)	±0.2% / 15°C / 0.14s
Operating voltage	0.7V
Operating current	1.0mA ~ 100mA

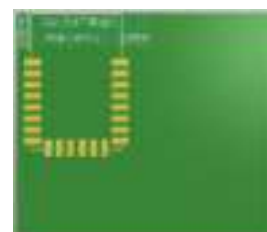
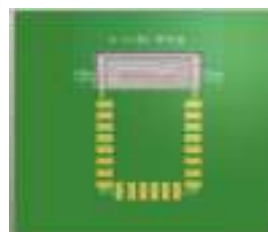
## 4 Antenna Info

### 4.1 Antenna Type

The XR2121-W module uses external ceramic PCU antenna on the P2 antenna interface.

### 4.2 Reduce antenna interference

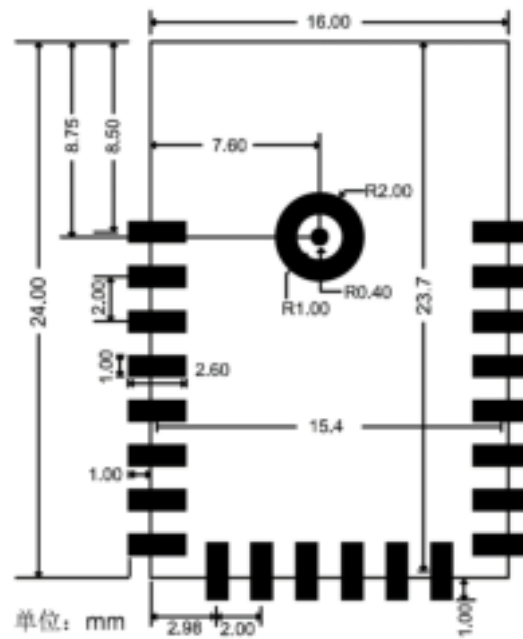
To ensure optimal RF performance, it is recommended that the distance between the antenna portion of the module and other metal parts be kept at least 20mm. If the environment of the antenna surrounding wrapped metal materials, etc., will largely attenuate the wireless signal, and thus deteriorate the 4G performance. Since the module is installed in the form of plug-in, needs to leave enough space for the antenna use.



# 5

## Module package size

Top view:



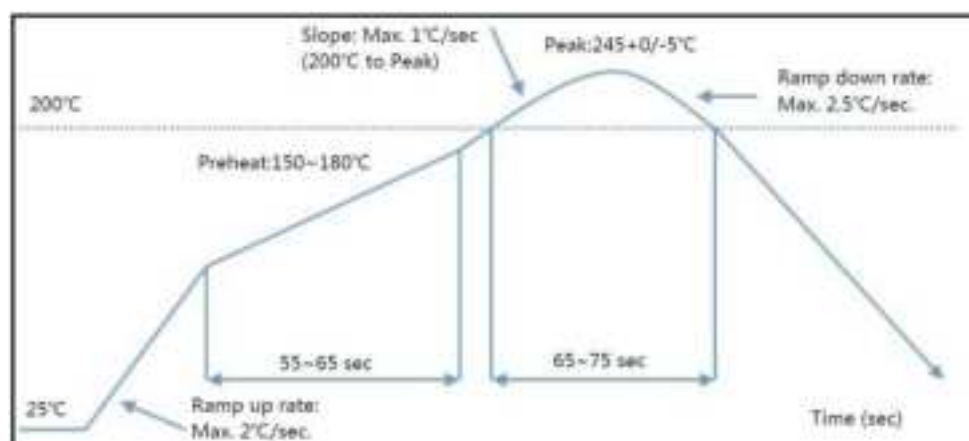
Note: The module package size is determined by the size of the module, and the size of the module is 1.0 mm.

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## 6 Recommended furnace temperature curve

Please refer to the following profile for SMT patching, peak temperature 245°C, reflow temperature profile as shown below: Refer to IPC/JEDEC standard; Peak Temperature: 250°C; Number of Times: 6/2 times



# 7 Appendix: Circuit Schematic

## Module MOQ and Packaging Information

Product Model	MOQ (PCS)	Packaging method	Package Quantity	Number of reels per
AP3721-B3	3600	Carrier tape reel	100	4

**Integration instructions for host product manufacturers according to KDB 996369 D03  
OEM Manual v01****2.2 List of applicable FCC rules FCC Part 15 Subpart C 15.247 & 15.209****2.3 Specific operational use conditions.**

The module can be used for mobile applications with a maximum 2.54dBi antenna. The manufacturer installing this module into their product must ensure that the final product complies with the FCC requirements by a technical assessment or evaluation to the FCC rules, including the transmitter operation. The host manufacturer has to be aware not to provide information to the end user regarding how to install or remove this RF module in the user's manual of the end product which integrates his module. The end user manual shall include all required regulatory information / warning as shown in this manual.

**2.4 Limited module procedures. Not applicable.**

The module is a Single module and complies with the requirement of FCC part 15.212.

**2.5 Trace antenna designs. Not applicable.**

The module as its own antenna, and doesn't need a host printed board microstrip trace antenna etc.

**2.6 RF exposure considerations.**

The module must be installed in the host equipment such that at least 20cm is maintained between the antenna and user's body, and if RF exposure statement or module layout is changed, then the host product manufacturer required to take responsibility of the module through a change in FCC ID or new application. The FCC ID of the module cannot be used on the final product. In these circumstances, the host manufacturer will be responsible for evaluating the end product (including the transmitter) and obtaining a separate FCC authorization.

**2.7 Antennas**

Antenna Specification are as follows:

Type: PCB Antenna

Gain: 2.54dBi Max

This device is intended only for host manufacturers under the following conditions: The module shall be only used with the internal antennas that has been originally tested and certified with this module. The antenna must be either permanently attached or employ a unique antenna coupler.

As long as the conditions above are met, further transmitter test will not be required. However, the host manufacturer is still responsible for testing their end-product for any additional compliance requirements required with his module installed for example, digital device emissions, PC peripheral requirements, etc.)

**2.8 Label and compliance information**

Host product manufacturers need to provide a physical or e-label stating "Contains FCC ID: 2A9TO-3721B3 with their finished product.

## 2.9 Information on test modes and additional testing requirements

Host manufacturers of a dedicated mission and spurious emission in test modes for a stand-alone modular transmitter in host, as well as for multi-silicon ramming modules or other transmitters in a host product.

Only when all the test results of test modes comply with FCC requirements, then the end product can be sold legally.

## 2.10 Additional testing, Part 15 subpart B disclaimer

The modular transmitter is only FCC authorized for FCC Part 15 Subpart C 15.247 & 15.209 & 15.407 and that the host product manufacturer is responsible for compliance to any other FCC rules that apply to the host not covered by the modular transmitter grant of certification.

If the grantee markets their product as being Part 15 Subpart B compliant when it also contains unintentional-radiator digital circuitry, then the grantee shall provide a notice stating that the final host product still requires Part 15 Subpart B compliance testing.

### FCC Requirement

Any changes or modifications not expressly approved by the party responsible for compliance could void the user's authority to operate the equipment.

This device complies with Part 15 of the FCC Rules. Operation is subject to the following two conditions:

- (1) this device may not cause harmful interference, and
- (2) this device must accept any interference received, including interference that may cause undesired operation.

Note: This equipment has been tested and found to comply with the limits for a Class B digital device, pursuant to Part 15 of the FCC Rules. These limits are designed to provide reasonable protection against harmful interference in a residential installation. This equipment generates, uses, and can radiate radio frequency energy, and if not installed and used in accordance with the instructions, may cause harmful interference to radio communications. However, there is no guarantee that interference will not occur in a particular installation. If this equipment does cause harmful interference to radio or television reception, which can be determined by turning the equipment off and on, the user is encouraged to try to correct the interference by one or more of the following measures:

- Reorient or relocate the receiving antenna.
- Increase the separation between the equipment and receiver.
- Connect the equipment into an outlet on a circuit different from that to which the receiver is connected.
- Consult the dealer or an experienced radio/TV technician for help.

This equipment complies with FCC radiation exposure limits set forth for an uncontrolled environment. This equipment should be installed and operated with a minimum distance of 20cm between the radiator & your body. This transmitter must not be co-located or operating in conjunction with any other antenna or transmitter.

CAUTION: Any changes or modifications not expressly approved could void the user's authority to operate the equipment."